

IN THE SPECIFICATION:

Please substitute the following paragraphs for the BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWINGS section of the specification:

While the specification concludes with claims particularly pointing out and distinctly claiming that which is regarded as the present invention, the advantages of this invention can be more readily ascertained from the following description of the invention when read in conjunction with the accompanying drawings in which:

FIG. 1 is a side view of one embodiment of the present invention;

FIG. 2 is a side view of a second embodiment of the present invention;

FIG. 2A is a top view of the second embodiment of the present invention shown in FIG. 2;

FIG. 3 is a side view of a third embodiment of the present invention;

FIG. 3A is an upside-down exploded perspective view of selected portions of the third embodiment; and

FIG. 4 is a side view of a fourth embodiment of the present invention.

Please substitute the following paragraph for the first full paragraph on Page 8 of the specification:

FIGS. 3 and 3A illustrate a third embodiment of the present invention designated as a wire bond style/flip chip attach assembly 300. Components which are common to the previous figures retain the same numeric designation. The assembly 300 comprises an inverted semiconductor die 12 having lower surface 14 with at least one bond pad 38 on the semiconductor die lower surface 14. As illustrated, the bond pads 38 are arranged in two rows extending down the longitudinal axis of die 12 being located transverse to the plane of the page, such an arrangement

commonly being used for a "leads over" connection to frame leads extending over the die in its normal, upright position. The semiconductor die lower surface 14 is bonded to the adaptor board upper surface 20 with an insulating, sealing adhesive 40. The adaptor board 18 includes at least one or more wire bond via 42 which is located in a position or positions aligned with the semiconductor die bond pads 38. Each individual wire bond 134 is connected to each corresponding individual semiconductor die bond pad 38. Each wire bond 134 extends from the semiconductor die bond pad 38 to a corresponding bond pad or lead 39 on the adaptor board lower surface 24, which communicates with adaptor board connectors 22 through circuit traces 23. The master board terminals 31 are in electrical communication with at least one adaptor board connector 22 extending substantially perpendicularly from the adapter board lower surface 24. Preferably, a sealant 44 encases the bond wires 134 and seals the wire bond via 42 to prevent contamination and damage to the wire bonds.